

METHOD AND SYSTEM FOR REDUCING He BACKSIDE FAULTS DURING WAFER PROCESSING

Abstract of the Disclosure

A method and system for processing a wafer is disclosed. The method includes receiving a wafer having a process side and a backside. The method further includes removing un-wanted particles from the backside of the wafer to prevent gaps from forming between the backside of the wafer and a chucking surface. The method also includes performing a specific processing task on the process side of the wafer after cleaning the backside of the wafer.